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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:	Okada et al.		
SERIAL NO.:	Not yet assigned	GROUP NO.:	Not yet assigned
FILING DATE:	Herewith	EXAMINER:	Not yet assigned
TITLE:	SYSTEM AND METHOD TO REDUCE METAL SERIES RESISTANCE OF BUMPED CHIP		

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Please enter the following Preliminary Amendment before beginning examination of the above-referenced patent application.

Please amend the above-identified patent application as follows:

Amendments to the Specification begin on page 2 of this paper;

Amendments to the Claims are reflected in the listing of claims that begins on page 3 of this paper; and

Remarks begin on page 7 of this paper.